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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 09/148,723  
 Priority Filing Date ..... September 3, 1998  
 Inventor ..... Warren M. Farnworth et al.  
 Assignee ..... Micron Technology, Inc.  
 Priority Group Art Unit ..... 3729  
 Priority Examiner ..... A. Tugbang  
 Attorney's Docket No. .... MI22-1839  
 Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

10/004172  
 10/09/01

**INFORMATION DISCLOSURE STATEMENT**

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending Application Serial No. 09/148,723, filed September 3, 1998, upon which the above-identified application relies for a priority dated under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). As a courtesy, Applicant submits copies of the cited article and foreign references for review.

Citation of these references is respectfully requested.

Respectfully submitted,

Date:

09/18/2001

*[Signature]*

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